

## Device Specification

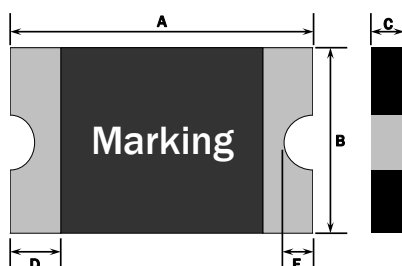
### ELECTRICAL CHARACTERISTICS

Part Number	Marking	$I_{hold}$ (A)	$I_{trip}$ (A)	$V_{max}$ (Vdc)	$I_{max}$ (A)	$Pd_{max}$ (W)	Maximum Time-to-Trip		Resistance	
							Current (A)	Time (Sec.)	$R_{min}$ ( $\Omega$ )	$R_{Imax}$ ( $\Omega$ )
0603L300/9SL	Z	3.00	6.00	9	50	0.60	8.00	1.00	0.003	0.030

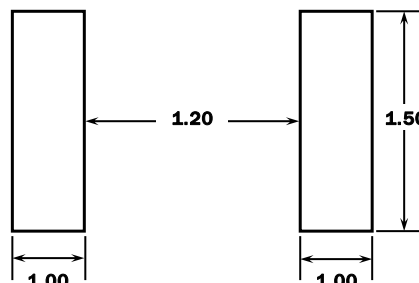
Note:  $I_{hold}$  = Hold current: maximum current device will pass without tripping in 20°C still air.  
 $I_{trip}$  = Trip Current: minimum current at which the device will trip in 20°C still air.  
 $V_{max}$  = Maximum voltage device can withstand without damage at rated current ( $I_{max}$ )  
 $I_{max}$  = Maximum fault current device can withstand without damage at rated voltage ( $V_{max}$ )  
 $Pd$  = Power dissipated from device when in the tripped state at 20°C still air.  
 $R_{min}$  = Minimum resistance of device in initial (un-soldered) state.  
 $R_{Imax}$  = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

**Caution** :Operation beyond the specified rating may result in damage and possible arcing and flame.

Figure



Solder Pad Layout (mm)



### PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
0603L300/9SL	1.40	1.80	0.60	1.00	0.40	1.00	0.15	0.50	--	0.40

## THERMAL DERATING CHART – I<sub>hold</sub>/I<sub>trip</sub> (Amps)

### Recommended Data

Part Number		Ambient Operation Temperature								
		-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
0603L300/9SL	I <sub>hold</sub>	4.70	4.15	3.60	3.00	2.50	2.20	2.00	1.65	1.20
	I <sub>trip</sub>	9.50	8.30	7.30	6.00	5.00	4.40	4.00	3.30	2.50

## AVERAGE TIME-CURRENT CURVE

